

CLAIMS

1. A polishing composition comprising:
 - a) an abrasive;
 - b) a fluoride salt; and
 - 5 c) an acetylenic alcohol.
2. The polishing composition of Claim 1 wherein the acetylenic alcohol has at least two hydroxyl substituents.
3. The polishing composition of Claim 2 wherein the acetylenic alcohol is 2,4,7,9-tetramethyl-5-decyn-4,7-diol.
- 10 4. The polishing composition of Claim 1 wherein the acetylenic alcohol is a C₄-C₂₂ alkyne.
5. The polishing composition of Claim 4 wherein the acetylenic alcohol is a C₁₂-C₁₆ alkyne.
6. The polishing composition of Claim 1 wherein the abrasive is a colloidal abrasive.
- 15 7. The polishing composition of Claim 6 wherein the colloidal abrasive is colloidal silica.
8. The polishing composition of Claim 1 wherein the fluoride salt is ammonium fluoride.
9. A method for chemical mechanical planarization of a substrate comprised of dielectric material, the method comprising the steps of:
 - 20 A) providing a substrate comprised of dielectric material in contact with a polishing pad;
 - B) providing a composition for chemical mechanical planarization comprising a) an abrasive; b) a fluoride salt; and c) an acetylenic alcohol; and
 - 25 C) polishing the substrate with the composition to effect at least partial planarization of the substrate.
10. The method of Claim 9 wherein the acetylenic alcohol of the composition has at least two hydroxyl substituents.
- 30 11. The method of Claim 10 wherein the acetylenic alcohol of the composition is 2,4,7,9-tetramethyl-5-decyn-4,7-diol.
12. The method of Claim 9 wherein the acetylenic alcohol of the composition is a C₄-C₂₂ alkyne.

13. The method of Claim 12 wherein the acetylenic alcohol of the composition is a C₁₂-C₁₆ alkyne.
14. The method of Claim 9 wherein the abrasive of the composition is a colloidal abrasive.
- 5 15. The method of Claim 14 wherein the colloidal abrasive is colloidal silica.
16. The method of Claim 9 wherein the fluoride salt of the composition is ammonium fluoride.

10 06354ZP USA.DOC